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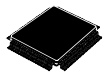
STM32F103xC, STM32F103xD, STM32F103xE

High-density performance line ARM®-based 32-bit MCU with 256 to 512KB Flash, USB, CAN, 11 timers, 3 ADCs, 13 communication interfaces

Datasheet –production data

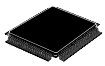
Features

- Core: ARM® 32-bit Cortex®-M3 CPU
  - 72 MHz maximum frequency, 1.25 DMIPS/MHz (Dhrystone 2.1) performance at 0 wait state memory access
  - Single-cycle multiplication and hardware division
- Memories
  - 256 to 512 Kbytes of Flash memory
  - up to 64 Kbytes of SRAM
  - Flexible static memory controller with 4 Chip Select. Supports Compact Flash, SRAM, PSRAM, NOR and NAND memories
  - LCD parallel interface, 8080/6800 modes
- Clock, reset and supply management
  - 2.0 to 3.6 V application supply and I/Os
  - POR, PDR, and programmable voltage detector (PVD)
  - 4-to-16 MHz crystal oscillator
  - Internal 8 MHz factory-trimmed RC
  - Internal 40 kHz RC with calibration
  - 32 kHz oscillator for RTC with calibration
- Low power
  - Sleep, Stop and Standby modes
  - V_{BAT} supply for RTC and backup registers
- 3 × 12-bit, 1 µs A/D converters (up to 21 channels)
  - Conversion range: 0 to 3.6 V
  - Triple-sample and hold capability
  - Temperature sensor
- 2 × 12-bit D/A converters
- DMA: 12-channel DMA controller
  - Supported peripherals: timers, ADCs, DAC, SDIO, I^2Ss, SPIs, I^2Cs and USARTs
- Debug mode
  - Serial wire debug (SWD) & JTAG interfaces
  - Cortex®-M3 Embedded Trace Macrocell™
- Up to 112 fast I/O ports
  - 51/80/112 I/Os, all mappable on 16 external interrupt vectors and almost all 5 V-tolerant



LQFP64 10 × 10 mm,
LQFP100 14 × 14 mm,
LQFP144 20 × 20 mm

WLCSP64



LFBGA100 10 × 10 mm
LFBGA144 10 × 10 mm

- Up to 11 timers
  - Up to four 16-bit timers, each with up to 4 IC/OC/PWM or pulse counter and quadrature (incremental) encoder input
  - 2 × 16-bit motor control PWM timers with dead-time generation and emergency stop
  - 2 × watchdog timers (Independent and Window)
  - SysTick timer: a 24-bit downcounter
  - 2 × 16-bit basic timers to drive the DAC
- Up to 13 communication interfaces
  - Up to 2 × I^2C interfaces (SMBus/PMBus)
  - Up to 5 USARTs (ISO 7816 interface, LIN, IrDA capability, modem control)
  - Up to 3 SPIs (18 Mbit/s), 2 with I^2S interface multiplexed
  - CAN interface (2.0B Active)
  - USB 2.0 full speed interface
  - SDIO interface
- CRC calculation unit, 96-bit unique ID
- ECOPACK® packages

Table 1.Device summary

Reference	Part number
STM32F103xC	STM32F103RC STM32F103VC STM32F103ZC
STM32F103xD	STM32F103RD STM32F103VD STM32F103ZD
STM32F103xE	STM32F103RE STM32F103ZE STM32F103VE

Contents

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1 Introduction

This datasheet provides the ordering information and mechanical device characteristics of the STM32F103xC, STM32F103xD and STM32F103xE high-density performance line microcontrollers. For more details on the whole STMicroelectronics STM32F103xC/D/E family, please refer to *Section 2.2: Full compatibility throughout the family*.

The high-density STM32F103xC/D/E datasheet should be read in conjunction with the STM32F10xxx reference manual.
For information on programming, erasing and protection of the internal Flash memory please refer to the *STM32F10xxx Flash programming manual.*
The reference and Flash programming manuals are both available from the STMicroelectronics website *www.st.com*.

For information on the Cortex®-M3 core please refer to the Cortex®-M3 Technical Reference Manual, available from the *www.arm.com* website at the following address: *http://infocenter.arm.com*.

2 Description

The STM32F103xC, STM32F103xD and STM32F103xE performance line family incorporates the high-performance ARM® Cortex®-M3 32-bit RISC core operating at a 72 MHz frequency, high-speed embedded memories (Flash memory up to 512 Kbytes and SRAM up to 64 Kbytes), and an extensive range of enhanced I/Os and peripherals connected to two APB buses. All devices offer three 12-bit ADCs, four general-purpose 16-bit timers plus two PWM timers, as well as standard and advanced communication interfaces: up to two I^2Cs, three SPIs, two I^2Ss, one SDIO, five USARTs, an USB and a CAN.

The STM32F103xC/D/E high-density performance line family operates in the –40 to +105 °C temperature range, from a 2.0 to 3.6 V power supply. A comprehensive set of power-saving mode allows the design of low-power applications.

These features make the STM32F103xC/D/E high-density performance line microcontroller family suitable for a wide range of applications such as motor drives, application control, medical and handheld equipment, PC and gaming peripherals, GPS platforms, industrial applications, PLCs, inverters, printers, scanners, alarm systems video intercom, and HVAC.

2.1 Device overview

The STM32F103xC/D/E high-density performance line family offers devices in six different package types: from 64 pins to 144 pins. Depending on the device chosen, different sets of peripherals are included, the description below gives an overview of the complete range of peripherals proposed in this family.

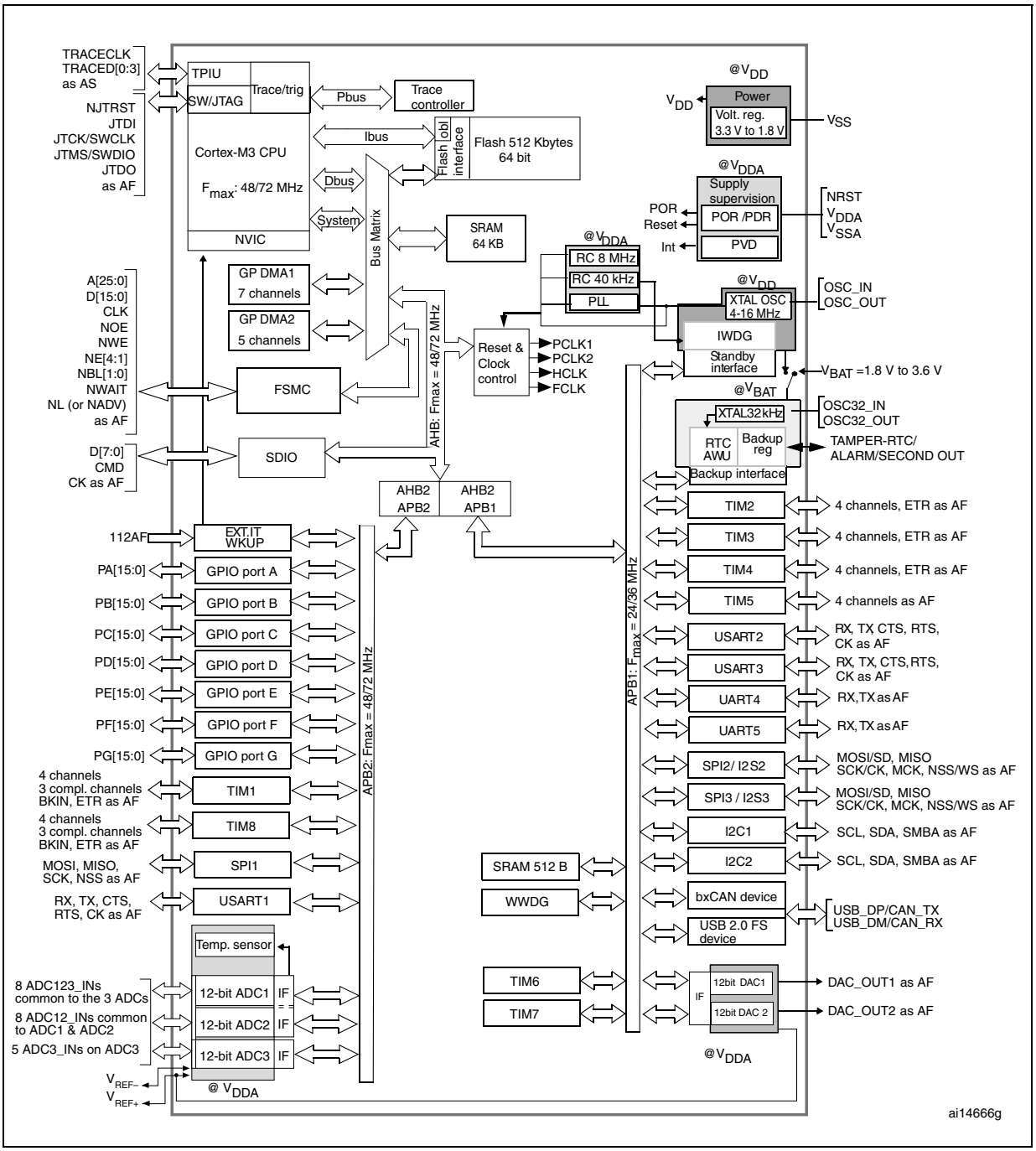
Figure 1 shows the general block diagram of the device family.

Table 2. STM32F103xC, STM32F103xD and STM32F103xE features and peripheral counts

Peripherals		STM32F103Rx			STM32F103Vx			STM32F103Zx		
Flash memory in Kbytes		256	384	512	256	384	512	256	384	512
SRAM in Kbytes		48	64(1)		48	64		48	64	
FSMC		No			Yes(2)			Yes		
Timers	General-purpose	4								
	Advanced-control	2								
	Basic	2								
Comm	SPI(I^2S)(3)	3(2)								
	I^2C	2								
	USART	5								
	USB	1								
	CAN	1								
	SDIO	1								
GPIOs		51			80			112		
12-bit ADC Number of channels		3 16			3 16			3 21		
12-bit DAC Number of channels		2 2								
CPU frequency		72 MHz								
Operating voltage		2.0 to 3.6 V								
Operating temperatures		Ambient temperatures: –40 to +85 °C /–40 to +105 °C (see *Table 10*) Junction temperature: –40 to + 125 °C (see *Table 10*)								
Package		LQFP64, WLCSP64			LQFP100, BGA100			LQFP144, BGA144		

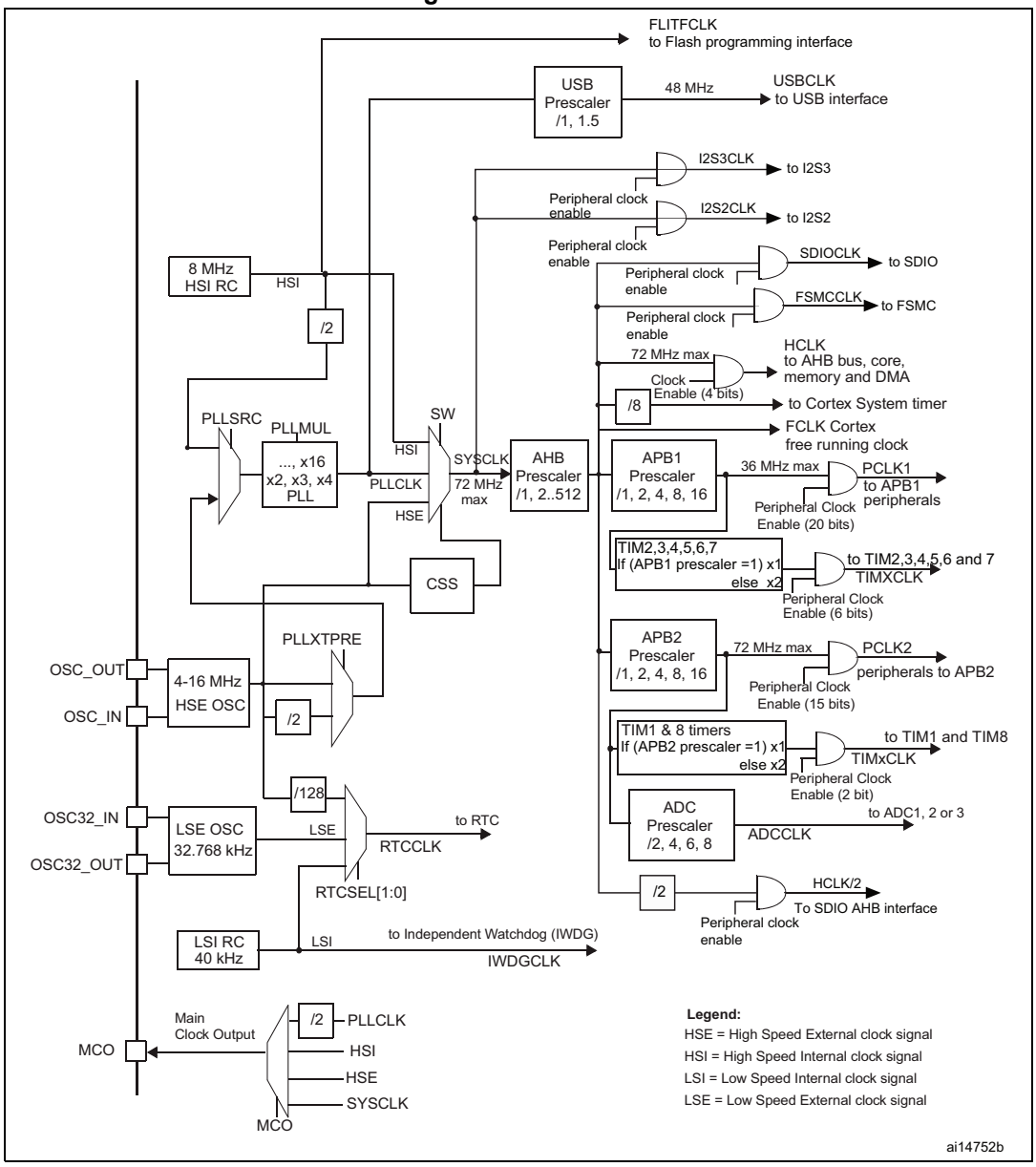
1. 64 KB RAM for 256 KB Flash are available on devices delivered in CSP packages only.
2. For the LQFP100 and BGA100 packages, only FSMC Bank1 and Bank2 are available. Bank1 can only support a multiplexed NOR/PSRAM memory using the NE1 Chip Select. Bank2 can only support a 16- or 8-bit NAND Flash memory using the NCE2 Chip Select. The interrupt line cannot be used since Port G is not available in this package.
3. The SPI2 and SPI3 interfaces give the flexibility to work in an exclusive way in either the SPI mode or the I^2S audio mode.

Figure 1. STM32F103xC, STM32F103xD and STM32F103xE performance line block diagram



1. T_A = –40 °C to +85 °C (suffix 6, see *Table 75*) or –40 °C to +105 °C (suffix 7, see *Table 75*), junction temperature up to 105 °C or 125 °C, respectively.
2. AF = alternate function on I/O port pin.9

Figure 2. Clock tree



1. When the HSI is used as a PLL clock input, the maximum system clock frequency that can be achieved is 64 MHz.
2. For the USB function to be available, both HSE and PLL must be enabled, with the USBCLK at 48 MHz.
3. To have an ADC conversion time of 1 µs, APB2 must be at 14 MHz, 28 MHz or 56 MHz.

2.2 Full compatibility throughout the family

The STM32F103xC/D/E is a complete family whose members are fully pin-to-pin, software and feature compatible. In the reference manual, the STM32F103x4 and STM32F103x6 are identified as low-density devices, the STM32F103x8 and STM32F103xB are referred to as medium-density devices and the STM32F103xC, STM32F103xD and STM32F103xE are referred to as high-density devices.

Low-density and high-density devices are an extension of the STM32F103x8/B medium-density devices, they are specified in the STM32F103x4/6 and STM32F103xC/D/E datasheets, respectively. Low-density devices feature lower Flash memory and RAM capacities, less timers and peripherals. High-density devices have higher Flash memory and RAM capacities, and additional peripherals like SDIO, FSMC, I^2S and DAC while remaining fully compatible with the other members of the family.

The STM32F103x4, STM32F103x6, STM32F103xC, STM32F103xD and STM32F103xE are a drop-in replacement for the STM32F103x8/B devices, allowing the user to try different memory densities and providing a greater degree of freedom during the development cycle.

Moreover, the STM32F103xx performance line family is fully compatible with all existing STM32F101xx access line and STM32F102xx USB access line devices.

Table 3. STM32F103xx family

<table>
<tr><th rowspan="3">Pinout</th><th colspan="2">Low-density devices</th><th colspan="2">Medium-density devices</th><th colspan="3">High-density devices</th></tr>
<tr><th>16 KB Flash</th><th>32 KB Flash(1)</th><th>64 KB Flash</th><th>128 KB Flash</th><th>256 KB Flash</th><th>384 KB Flash</th><th>512 KB Flash</th></tr>
<tr><th>6 KB RAM</th><th>10 KB RAM</th><th>20 KB RAM</th><th>20 KB RAM</th><th>48 RAM</th><th>64 KB RAM</th><th>64 KB RAM</th></tr>
<tr><td>144</td><td colspan="2" rowspan="2"></td><td colspan="2" rowspan="3">3 × USARTs
3 × 16-bit timers
2 × SPIs, 2 × I2Cs, USB, CAN, 1 × PWM timer
2 × ADCs</td><td colspan="3" rowspan="2">5 × USARTs
4 × 16-bit timers, 2 × basic timers
3 × SPIs, 2 × I2Ss, 2 × I2Cs
USB, CAN, 2 × PWM timers
3 × ADCs, 2 × DACs, 1 × SDIO
FSMC (100- and 144-pin packages(2))</td></tr>
<tr><td>100</td></tr>
<tr><td>64</td><td colspan="2" rowspan="3">2 × USARTs
2 × 16-bit timers
1 × SPI, 1 × I2C, USB, CAN, 1 × PWM timer
2 × ADCs</td><td colspan="3" rowspan="2"></td></tr>
<tr><td>48</td></tr>
<tr><td>36</td><td colspan="4"></td></tr>
</table>

1. For orderable part numbers that do not show the A internal code after the temperature range code (6 or 7), the reference datasheet for electrical characteristics is that of the STM32F103x8/B medium-density devices.
2. Ports F and G are not available in devices delivered in 100-pin packages.

2.3 Overview

2.3.1 ARM® Cortex®-M3 core with embedded Flash and SRAM

The ARM Cortex®-M3 processor is the latest generation of ARM processors for embedded systems. It has been developed to provide a low-cost platform that meets the needs of MCU implementation, with a reduced pin count and low-power consumption, while delivering outstanding computational performance and an advanced system response to interrupts.

The ARM Cortex®-M3 32-bit RISC processor features exceptional code-efficiency, delivering the high-performance expected from an ARM core in the memory size usually associated with 8- and 16-bit devices.

With its embedded ARM core, STM32F103xC, STM32F103xD and STM32F103xE performance line family is compatible with all ARM tools and software.

Figure 1 shows the general block diagram of the device family.

2.3.2 Embedded Flash memory

Up to 512 Kbytes of embedded Flash is available for storing programs and data.

2.3.3 CRC (cyclic redundancy check) calculation unit

The CRC (cyclic redundancy check) calculation unit is used to get a CRC code from a 32-bit data word and a fixed generator polynomial.

Among other applications, CRC-based techniques are used to verify data transmission or storage integrity. In the scope of the EN/IEC 60335-1 standard, they offer a means of verifying the Flash memory integrity. The CRC calculation unit helps compute a signature of the software during runtime, to be compared with a reference signature generated at link-time and stored at a given memory location.

2.3.4 Embedded SRAM

Up to 64 Kbytes of embedded SRAM accessed (read/write) at CPU clock speed with 0 wait states.

2.3.5 FSMC (flexible static memory controller)

The FSMC is embedded in the STM32F103xC, STM32F103xD and STM32F103xE performance line family. It has four Chip Select outputs supporting the following modes: PC Card/Compact Flash, SRAM, PSRAM, NOR and NAND.

Functionality overview:

- The three FSMC interrupt lines are ORed in order to be connected to the NVIC
- Write FIFO
- Code execution from external memory except for NAND Flash and PC Card
- The targeted frequency, f_{CLK}, is HCLK/2, so external access is at 36 MHz when HCLK is at 72 MHz and external access is at 24 MHz when HCLK is at 48 MHz

2.3.6 LCD parallel interface

The FSMC can be configured to interface seamlessly with most graphic LCD controllers. It supports the Intel 8080 and Motorola 6800 modes, and is flexible enough to adapt to specific LCD interfaces. This LCD parallel interface capability makes it easy to build cost-effective graphic applications using LCD modules with embedded controllers or high-performance solutions using external controllers with dedicated acceleration.

2.3.7 Nested vectored interrupt controller (NVIC)

The STM32F103xC, STM32F103xD and STM32F103xE performance line embeds a nested vectored interrupt controller able to handle up to 60 maskable interrupt channels (not including the 16 interrupt lines of Cortex®-M3) and 16 priority levels.

- Closely coupled NVIC gives low latency interrupt processing
- Interrupt entry vector table address passed directly to the core
- Closely coupled NVIC core interface
- Allows early processing of interrupts
- Processing of *late arriving* higher priority interrupts
- Support for tail-chaining
- Processor state automatically saved
- Interrupt entry restored on interrupt exit with no instruction overhead

This hardware block provides flexible interrupt management features with minimal interrupt latency.

2.3.8 External interrupt/event controller (EXTI)

The external interrupt/event controller consists of 19 edge detector lines used to generate interrupt/event requests. Each line can be independently configured to select the trigger event (rising edge, falling edge, both) and can be masked independently. A pending register maintains the status of the interrupt requests. The EXTI can detect an external line with a pulse width shorter than the Internal APB2 clock period. Up to 112 GPIOs can be connected to the 16 external interrupt lines.

2.3.9 Clocks and startup

System clock selection is performed on startup, however the internal RC 8 MHz oscillator is selected as default CPU clock on reset. An external 4-16 MHz clock can be selected, in which case it is monitored for failure. If failure is detected, the system automatically switches back to the internal RC oscillator. A software interrupt is generated if enabled. Similarly, full interrupt management of the PLL clock entry is available when necessary (for example with failure of an indirectly used external oscillator).

Several prescalers allow the configuration of the AHB frequency, the high speed APB (APB2) and the low speed APB (APB1) domains. The maximum frequency of the AHB and the high speed APB domains is 72 MHz. The maximum allowed frequency of the low speed APB domain is 36 MHz. See *Figure 2* for details on the clock tree.

2.3.10 Boot modes

At startup, boot pins are used to select one of three boot options:

- Boot from user Flash: you have an option to boot from any of two memory banks. By default, boot from Flash memory bank 1 is selected. You can choose to boot from Flash memory bank 2 by setting a bit in the option bytes.
- Boot from system memory
- Boot from embedded SRAM

The boot loader is located in system memory. It is used to reprogram the Flash memory by using USART1.

2.3.11 Power supply schemes

- V_{DD} = 2.0 to 3.6 V: external power supply for I/Os and the internal regulator. Provided externally through V_{DD} pins.
- V_{SSA}, V_{DDA} = 2.0 to 3.6 V: external analog power supplies for ADC, DAC, Reset blocks, RCs and PLL (minimum voltage to be applied to VDDA is 2.4 V when the ADC or DAC is used). V_{DDA} and V_{SSA} must be connected to V_{DD} and V_{SS}, respectively.
- V_{BAT} = 1.8 to 3.6 V: power supply for RTC, external clock 32 kHz oscillator and backup registers (through power switch) when V_{DD} is not present.

For more details on how to connect power pins, refer to *Figure 12: Power supply scheme*.

2.3.12 Power supply supervisor

The device has an integrated power-on reset (POR)/power-down reset (PDR) circuitry. It is always active, and ensures proper operation starting from/down to 2 V. The device remains in reset mode when V_{DD} is below a specified threshold, $V_{POR/PDR}$, without the need for an external reset circuit.

The device features an embedded programmable voltage detector (PVD) that monitors the V_{DD}/V_{DDA} power supply and compares it to the V_{PVD} threshold. An interrupt can be generated when V_{DD}/V_{DDA} drops below the V_{PVD} threshold and/or when V_{DD}/V_{DDA} is higher than the V_{PVD} threshold. The interrupt service routine can then generate a warning message and/or put the MCU into a safe state. The PVD is enabled by software. Refer to *Table 12: Embedded reset and power control block characteristics* for the values of $V_{POR/PDR}$ and V_{PVD}.

2.3.13 Voltage regulator

The regulator has three operation modes: main (MR), low-power (LPR) and power down.

- MR is used in the nominal regulation mode (Run)
- LPR is used in the Stop modes.
- Power down is used in Standby mode: the regulator output is in high impedance: the kernel circuitry is powered down, inducing zero consumption (but the contents of the registers and SRAM are lost)

This regulator is always enabled after reset. It is disabled in Standby mode.

2.3.14 Low-power modes

The STM32F103xC, STM32F103xD and STM32F103xE performance line supports three low-power modes to achieve the best compromise between low-power consumption, short startup time and available wakeup sources:

- **Sleep** mode

  In Sleep mode, only the CPU is stopped. All peripherals continue to operate and can wake up the CPU when an interrupt/event occurs.

- **Stop** mode

  Stop mode achieves the lowest power consumption while retaining the content of SRAM and registers. All clocks in the 1.8 V domain are stopped, the PLL, the HSI RC and the HSE crystal oscillators are disabled. The voltage regulator can also be put either in normal or in low-power mode.
  The device can be woken up from Stop mode by any of the EXTI line. The EXTI line source can be one of the 16 external lines, the PVD output, the RTC alarm or the USB wakeup.

- **Standby** mode

  The Standby mode is used to achieve the lowest power consumption. The internal voltage regulator is switched off so that the entire 1.8 V domain is powered off. The PLL, the HSI RC and the HSE crystal oscillators are also switched off. After entering Standby mode, SRAM and register contents are lost except for registers in the Backup domain and Standby circuitry.

  The device exits Standby mode when an external reset (NRST pin), an IWDG reset, a rising edge on the WKUP pin, or an RTC alarm occurs.

Note: The RTC, the IWDG, and the corresponding clock sources are not stopped by entering Stop or Standby mode.

2.3.15 DMA

The flexible 12-channel general-purpose DMAs (7 channels for DMA1 and 5 channels for DMA2) are able to manage memory-to-memory, peripheral-to-memory and memory-to-peripheral transfers. The two DMA controllers support circular buffer management, removing the need for user code intervention when the controller reaches the end of the buffer.

Each channel is connected to dedicated hardware DMA requests, with support for software trigger on each channel. Configuration is made by software and transfer sizes between source and destination are independent.

The DMA can be used with the main peripherals: SPI, I^2C, USART, general-purpose, basic and advanced-control timers TIMx, DAC, I^2S, SDIO and ADC.

2.3.16 RTC (real-time clock) and backup registers

The RTC and the backup registers are supplied through a switch that takes power either on V_{DD} supply when present or through the V_{BAT} pin. The backup registers are forty-two 16-bit registers used to store 84 bytes of user application data when V_{DD} power is not present. They are not reset by a system or power reset, and they are not reset when the device wakes up from the Standby mode.

The real-time clock provides a set of continuously running counters which can be used with suitable software to provide a clock calendar function, and provides an alarm interrupt and a

periodic interrupt. It is clocked by a 32.768 kHz external crystal, resonator or oscillator, the internal low-power RC oscillator or the high-speed external clock divided by 128. The internal low-speed RC has a typical frequency of 40 kHz. The RTC can be calibrated using an external 512 Hz output to compensate for any natural quartz deviation. The RTC features a 32-bit programmable counter for long term measurement using the Compare register to generate an alarm. A 20-bit prescaler is used for the time base clock and is by default configured to generate a time base of 1 second from a clock at 32.768 kHz.

2.3.17 Timers and watchdogs

The high-density STM32F103xC/D/E performance line devices include up to two advanced-control timers, up to four general-purpose timers, two basic timers, two watchdog timers and a SysTick timer.

Table 4 compares the features of the advanced-control, general-purpose and basic timers.

Table 4. High-density timer feature comparison

Timer	Counter resolution	Counter type	Prescaler factor	DMA request generation	Capture/compare channels	Complementary outputs
TIM1, TIM8	16-bit	Up, down, up/down	Any integer between 1 and 65536	Yes	4	Yes
TIM2, TIM3, TIM4, TIM5	16-bit	Up, down, up/down	Any integer between 1 and 65536	Yes	4	No
TIM6, TIM7	16-bit	Up	Any integer between 1 and 65536	Yes	0	No

Advanced-control timers (TIM1 and TIM8)

The two advanced-control timers (TIM1 and TIM8) can each be seen as a three-phase PWM multiplexed on 6 channels. They have complementary PWM outputs with programmable inserted dead-times. They can also be seen as a complete general-purpose timer. The 4 independent channels can be used for:

- Input capture
- Output compare
- PWM generation (edge or center-aligned modes)
- One-pulse mode output

If configured as a standard 16-bit timer, it has the same features as the TIMx timer. If configured as the 16-bit PWM generator, it has full modulation capability (0-100%).

In debug mode, the advanced-control timer counter can be frozen and the PWM outputs disabled to turn off any power switch driven by these outputs.

Many features are shared with those of the general-purpose TIM timers which have the same architecture. The advanced-control timer can therefore work together with the TIM timers via the Timer Link feature for synchronization or event chaining.

General-purpose timers (TIMx)

There are up to 4 synchronizable general-purpose timers (TIM2, TIM3, TIM4 and TIM5) embedded in the STM32F103xC, STM32F103xD and STM32F103xE performance line devices. These timers are based on a 16-bit auto-reload up/down counter, a 16-bit prescaler and feature 4 independent channels each for input capture/output compare, PWM or one-pulse mode output. This gives up to 16 input captures / output compares / PWMs on the largest packages.
The general-purpose timers can work together with the advanced-control timer via the Timer Link feature for synchronization or event chaining. Their counter can be frozen in debug mode. Any of the general-purpose timers can be used to generate PWM outputs. They all have independent DMA request generation.

These timers are capable of handling quadrature (incremental) encoder signals and the digital outputs from 1 to 3 hall-effect sensors.

Basic timers TIM6 and TIM7

These timers are mainly used for DAC trigger generation. They can also be used as a generic 16-bit time base.

Independent watchdog

The independent watchdog is based on a 12-bit downcounter and 8-bit prescaler. It is clocked from an independent 40 kHz internal RC and as it operates independently from the main clock, it can operate in Stop and Standby modes. It can be used either as a watchdog to reset the device when a problem occurs, or as a free running timer for application timeout management. It is hardware or software configurable through the option bytes. The counter can be frozen in debug mode.

Window watchdog

The window watchdog is based on a 7-bit downcounter that can be set as free running. It can be used as a watchdog to reset the device when a problem occurs. It is clocked from

the main clock. It has an early warning interrupt capability and the counter can be frozen in debug mode.

SysTick timer

This timer is dedicated to real-time operating systems, but could also be used as a standard down counter. It features:

- A 24-bit down counter
- Autoreload capability
- Maskable system interrupt generation when the counter reaches 0.
- Programmable clock source

2.3.18 I²C bus

Up to two I²C bus interfaces can operate in multimaster and slave modes. They can support standard and fast modes.

They support 7/10-bit addressing mode and 7-bit dual addressing mode (as slave). A hardware CRC generation/verification is embedded.

They can be served by DMA and they support SMBus 2.0/PMBus.

2.3.19 Universal synchronous/asynchronous receiver transmitters (USARTs)

The STM32F103xC, STM32F103xD and STM32F103xE performance line embeds three universal synchronous/asynchronous receiver transmitters (USART1, USART2 and USART3) and two universal asynchronous receiver transmitters (UART4 and UART5).

These five interfaces provide asynchronous communication, IrDA SIR ENDEC support, multiprocessor communication mode, single-wire half-duplex communication mode and have LIN Master/Slave capability.

The USART1 interface is able to communicate at speeds of up to 4.5 Mbit/s. The other available interfaces communicate at up to 2.25 Mbit/s.

USART1, USART2 and USART3 also provide hardware management of the CTS and RTS signals, Smart Card mode (ISO 7816 compliant) and SPI-like communication capability. All interfaces can be served by the DMA controller except for UART5.

2.3.20 Serial peripheral interface (SPI)

Up to three SPIs are able to communicate up to 18 Mbits/s in slave and master modes in full-duplex and simplex communication modes. The 3-bit prescaler gives 8 master mode frequencies and the frame is configurable to 8 bits or 16 bits. The hardware CRC generation/verification supports basic SD Card/MMC modes.

All SPIs can be served by the DMA controller.

2.3.21 Inter-integrated sound (I^2S)

Two standard I^2S interfaces (multiplexed with SPI2 and SPI3) are available, that can be operated in master or slave mode. These interfaces can be configured to operate with 16/32 bit resolution, as input or output channels. Audio sampling frequencies from 8 kHz up to 48 kHz are supported. When either or both of the I^2S interfaces is/are configured in master

mode, the master clock can be output to the external DAC/CODEC at 256 times the sampling frequency.

2.3.22 SDIO

An SD/SDIO/MMC host interface is available, that supports MultiMediaCard System Specification Version 4.2 in three different databus modes: 1-bit (default), 4-bit and 8-bit. The interface allows data transfer at up to 48 MHz in 8-bit mode, and is compliant with SD Memory Card Specifications Version 2.0.
The SDIO Card Specification Version 2.0 is also supported with two different databus modes: 1-bit (default) and 4-bit.

The current version supports only one SD/SDIO/MMC4.2 card at any one time and a stack of MMC4.1 or previous.

In addition to SD/SDIO/MMC, this interface is also fully compliant with the CE-ATA digital protocol Rev1.1.

2.3.23 Controller area network (CAN)

The CAN is compliant with specifications 2.0A and B (active) with a bit rate up to 1 Mbit/s. It can receive and transmit standard frames with 11-bit identifiers as well as extended frames with 29-bit identifiers. It has three transmit mailboxes, two receive FIFOs with 3 stages and 14 scalable filter banks.

2.3.24 Universal serial bus (USB)

The STM32F103xC, STM32F103xD and STM32F103xE performance line embed a USB device peripheral compatible with the USB full-speed 12 Mbs. The USB interface implements a full-speed (12 Mbit/s) function interface. It has software-configurable endpoint setting and suspend/resume support. The dedicated 48 MHz clock is generated from the internal main PLL (the clock source must use a HSE crystal oscillator).

2.3.25 GPIOs (general-purpose inputs/outputs)

Each of the GPIO pins can be configured by software as output (push-pull or open-drain), as input (with or without pull-up or pull-down) or as peripheral alternate function. Most of the GPIO pins are shared with digital or analog alternate functions. All GPIOs are high current-capable.

The I/Os alternate function configuration can be locked if needed following a specific sequence in order to avoid spurious writing to the I/Os registers.

2.3.26 ADC (analog to digital converter)

Three 12-bit analog-to-digital converters are embedded into STM32F103xC, STM32F103xD and STM32F103xE performance line devices and each ADC shares up to 21 external channels, performing conversions in single-shot or scan modes. In scan mode, automatic conversion is performed on a selected group of analog inputs.

Additional logic functions embedded in the ADC interface allow:

- Simultaneous sample and hold
- Interleaved sample and hold
- Single shunt

The ADC can be served by the DMA controller.

An analog watchdog feature allows very precise monitoring of the converted voltage of one, some or all selected channels. An interrupt is generated when the converted voltage is outside the programmed thresholds.

The events generated by the general-purpose timers (TIMx) and the advanced-control timers (TIM1 and TIM8) can be internally connected to the ADC start trigger and injection trigger, respectively, to allow the application to synchronize A/D conversion and timers.

2.3.27 DAC (digital-to-analog converter)

The two 12-bit buffered DAC channels can be used to convert two digital signals into two analog voltage signal outputs. The chosen design structure is composed of integrated resistor strings and an amplifier in inverting configuration.

This dual digital Interface supports the following features:

- two DAC converters: one for each output channel
- 8-bit or 12-bit monotonic output
- left or right data alignment in 12-bit mode
- synchronized update capability
- noise-wave generation
- triangular-wave generation
- dual DAC channel independent or simultaneous conversions
- DMA capability for each channel
- external triggers for conversion
- input voltage reference V_{REF+}

Eight DAC trigger inputs are used in the STM32F103xC, STM32F103xD and STM32F103xE performance line family. The DAC channels are triggered through the timer update outputs that are also connected to different DMA channels.

2.3.28 Temperature sensor

The temperature sensor has to generate a voltage that varies linearly with temperature. The conversion range is between 2 V < V_{DDA} < 3.6 V. The temperature sensor is internally connected to the ADC1_IN16 input channel which is used to convert the sensor output voltage into a digital value.

2.3.29 Serial wire JTAG debug port (SWJ-DP)

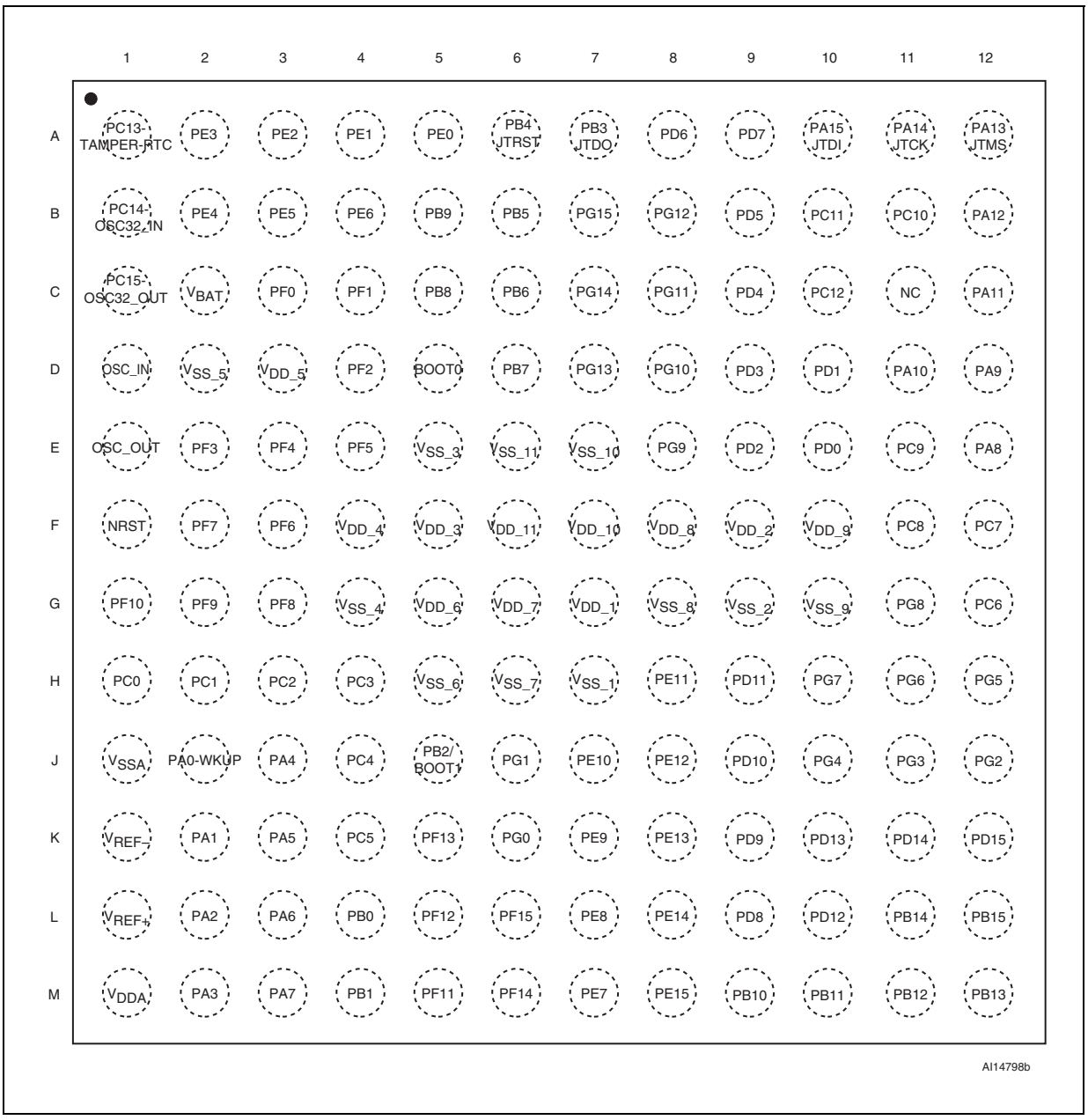
The ARM SWJ-DP Interface is embedded, and is a combined JTAG and serial wire debug port that enables either a serial wire debug or a JTAG probe to be connected to the target. The JTAG TMS and TCK pins are shared respectively with SWDIO and SWCLK and a specific sequence on the TMS pin is used to switch between JTAG-DP and SW-DP.

2.3.30 Embedded Trace Macrocell™

The ARM® Embedded Trace Macrocell provides a greater visibility of the instruction and data flow inside the CPU core by streaming compressed data at a very high rate from the STM32F10xxx through a small number of ETM pins to an external hardware trace port analyzer (TPA) device. The TPA is connected to a host computer using USB, Ethernet, or any other high-speed channel. Real-time instruction and data flow activity can be recorded and then formatted for display on the host computer running debugger software. TPA hardware is commercially available from common development tool vendors. It operates with third party debugger software tools.

3 Pinouts and pin descriptions

Figure 3. STM32F103xC/D/E BGA144 ballout



1. The above figure shows the package top view.